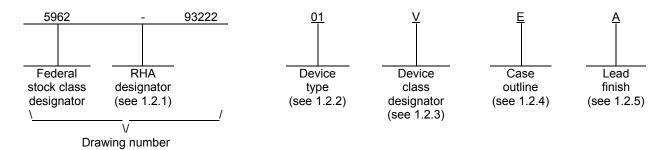
									VE VIOI	ONS										
LTR	DESCRIPTION										DATE (YR-MO-DA)			APPROVED						
А	Table I; for power supply rejection ratio test, change limit from "0.01 %/V minimum" to "0.01 %/V maximum". Changes in accordance with N.O.R. 5962-R011-94.						imit fro	m	93-10-18			M. A. FRYE								
В	Draw	ing upo	dated to	o reflec	t curre	nt requ	iremen	ts. Red	drawn.	- ro				02-0	1-08			R. M	ONNIN	
С	Make changes to 1.2.4, 1.4, and Table IIA. Add junction tempower dissipation limits under 1.3. Add Table IIB. Under par 4.4.2.1, delete test condition B and substitute test condition D Add subgroups 4, 5, 6, 10, and 11 to Table I and Table IIA.						ragrapl D.	re and ns 4.2.	1 and		11-0)2-28			C SAFFLE					
REV																				
REV SHEET																				
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SHEET REV				REV	,		C	C	C	C	C	C	C	C	С	C	C			
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SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A	NDAR			SHE PREI DAN	ET PAREI N WON	BY	1					6	7 DLA I	8 LAND	9 AND OHIO	10 MAF	11 RITIM 218-3	_		
SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STAI MICRO DRA	NDAR OCIRO AWIN	CUIT G		SHE PREI DAN CHE SAN	PAREIN WON	BY ROONI	1					6	7 DLA I	8 LAND	9 AND OHIO	10 MAF O 432	11 RITIM 218-3	_		
SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STAI MICRO DRA THIS DRAWIN FOR U	NDAR OCIRC AWING NG IS A ISE BY A RTMEN NCIES C	CUIT G VAILAE ALL TS OF THE	<u> </u>	SHE PREI DAN CHE SAN APPI MIC	PAREIN WON CKED NDRA ROVEI	BY ROONI D BY A. FRY	EY	2		MIC VO	SROC LTAG	COCCIRCU	DLA DLUM http	BUS, :://ww	9 AND O AND O OHIO OW.ds	D MAF D 432 CC.dl	218-3 a.mil	990 ER,	CY-TC	
SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STAI MICRO DRA THIS DRAWIN FOR U DEPAI AND AGEN DEPARTMEN	NDAR OCIRC AWING NG IS A ISE BY A RTMEN NCIES C	CUIT G VAILAE ALL TS DF THE DEFEN	<u> </u>	PREI DAM CHEI SAM APPI MIC	PAREIN WON CKED NDRA ROVEICHAEL WING	BY ROONI D BY A. FRY APPRO 93-1	EY /E DVAL E	2		MIC VOI VOI	SROC LTAG	CIRCUGE-TOGE, M	DLA DLUM http	BLAND BBUS, D://ww	9 AND O AND O OHIO OW.ds	D MAF D 432 cc.dl	218-3 a.mil	ER, JENC		

DSCC FORM 2233 APR 97

1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.
 - 1.2 PIN. The PIN is as shown in the following example:



- 1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	AD652	V/F and F/V converter

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as follows:

Device class

Device requirements documentation

M

Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A

Q or V

Certification and qualification to MIL-PRF-38535

1.2.4 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
Е	GDIP1-T16	16	Dual-in-line

1.2.5 <u>Lead finish</u>. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

STANDARD	
MICROCIRCUIT DRAWING	ì

DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990

SIZE A		5962-93222
	REVISION LEVEL C	SHEET 2

1.3 Absolute maximum ratings. 1/

Supply voltage (+V _S to -V _S)	36 V dc
Open collector output voltage (above digital ground)	36 V dc
Open collector output current	50 mA
Lead temperature (soldering 10 seconds)	300°C
Maximum junction temperature (T _J)	+160°C
Power dissipation (P _D)	540 mW
Storage temperature range	-65°C to +150°C
Thermal resistance junction-to-case (Θ _{JC})	25°C/W
Thermal resistance junction-to ambient (Θ_{JA})	100°C/W <u>2</u> /

1.4 Recommended operating conditions.

Supply voltage (±V _S)	±6 V to ±15 V
Ambient operating temperature range	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at https://assist.daps.dla.mil/quicksearch/ or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

Measurement taken under absolute worst case condition of still air while mounted above the printed circuit board (PCB) to minimize PCB mounting heat sink effects.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-93222
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 3

^{1/} Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.
 - 3.2.1 Case outline. The case outline shall be in accordance with 1.2.4 herein.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.
- 3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.
- 3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change for device class M</u>. For device class M, notification to DLA Land and Maritime -VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.
- 3.9 <u>Verification and review for device class M.</u> For device class M, DLA Land and Maritime, DLA Land and Maritime's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device class M.</u> Device class M devices covered by this drawing shall be in microcircuit group number 57 (see MIL-PRF-38535, appendix A).

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-93222
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 4

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C \pm V _S = \pm 15 V	Group A subgroups	Device type	Lir	nits	Unit
		unless otherwise specified			Min	Max	
Linearity error <u>2</u> / <u>3</u> /	LE	f _{CLOCK} = 1 MHZ, V _{IN} = .01 V; 1.0 V to 9.4 V in 1.05 V steps	1,2,3	01		0.02	% of FS
		f _{CLOCK} = 4 MHZ, V _{IN} = .01 V; 1.0 V to 9.4 V in 1.05 V steps				0.05	
Gain error <u>2</u> /	AE	f _{CLOCK} = 1 MHZ, V _{IN} = .01 V, 9.4 V	1	01		1	% of FS
		f _{CLOCK} = 4 MHZ, V _{IN} = .01 V, 9.4 V				1.5	
Gain temperature coefficient	TCA	f _{CLOCK} = 1 MHZ, V _{IN} = .01 V, 9.4 V	2,3	01		±50	ppm/°C
		f _{CLOCK} = 4 MHZ, V _{IN} = .01 V, 9.4 V				±75	
Power supply rejection <u>3</u> / ratio	PSRR	$12 \text{ V} \le \text{V}_{S} \le 18 \text{ V},$ $f_{CLOCK} = 4 \text{ MHZ}$	2,3	01		0.01	%/V
Input offset voltage 4/ (transfer function, RTI)	V _{IO}	V _{IN} = 0.1 V, 9.4 V, f _{CLOCK} = 1 MHz, 4 MHZ	1	01		±3	mV
Input offset voltage (RTI) temperature coefficient	TCV _{IO}	f _{CLOCK} = 1 MHZ	2,3	01		±50	μV/°C
Input resistor	R _{IN}		1	01	19.8	20.2	kΩ
Input resistor temperature	TCRIN		2,3	01		±100	ppm/°C
Op amp input bias 3/	I _{IB}	V _{IN} = 0 V, inverting input	1	01		±20	nA
current			2,3			±40	
		V _{IN} = 0 V, noninverting input	1,2,3			50	
Op amp input offset <u>3</u> / current	los	V _{IN} = 0 V	1,2,3	01		70	nA
Op amp input offset 3/ voltage	Vos	V _{IN} = 0 V	1,2,3	01		±3	mV

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-93222
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 5

TABLE I. <u>Electrical performance characteristics</u> – Continued.

Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C \pm V _S = \pm 15 V	Group A subgroups	Device type	Lir	nits	Unit
		unless otherwise specified			Min	Max	
Op amp output voltage 3/	V _R	$V_S = \pm 15 \text{ V}$, op amp railed high	1,2 3	01	11 10.3		V
range		$V_S = \pm 15 \text{ V}$, op amp	1,3	-	10.0	-1 -0.6	-
Max clock frequency 3/	fCLOCK	railed low V _{IN} = 0.01 V, 9.4 V	4,5,6	01	4	-0.6	MHz
Clock threshold voltage	V _{CT}	Referred to DIGITAL GND pin	1,2,3	01	0.8	2.0	V
Clock input current 3/	Ic	CLOCK IN pin = 0 V	1,2,3	01		20	μА
Low level output 3/ voltage 1	V _{OL1}	I _{OUT} = 15 mA	1,2,3	01		0.8	V
		I _{OUT} = 10 mA				0.4	
Low level output voltage 2	V _{OL2}	I _{OUT} = 8 mA	1,2,3			0.4	
Leakage current 3/	IL	V _{OUT} = 36 V	1,2,3	01		10	μА
Reference voltage	V _{REF}	I _{REF} = 0 mA	1	01	4.95	5.05	٧
Reference voltage temperature coefficient	TCV _{REF}	I _{REF} = 0 mA	2,3	01		±100	ppm/°C
Quiescent current 3/	±ISS	$V_S = \pm 15 \text{ V}, V_{IN} = 0.1 \text{ V}$	1,2,3	01		±15	mA
Delay time positive clock 3/	to	f _{CLOCK} = 200 kHz,	9	01	150	250	ns
edge to output pulse	t _D	COS pin to +V _S pin	10,11		150	350	113
Output pulse width 3/	t _{PW}	C _{OS} = 300 pF	9,10,11	01	1	2	μS

- $\underline{1}/$ 0.1 μF decoupling capacitors from +V_S to ground and -V_S to ground.
- 2/ Nonlinearity is defined as the deviation from a straight line from zero to full scale, expressed as a fraction of full scale.
- 3/ Additional test parameters applicable to final electrical and group A subgroups 2, 3, 5, 6, 10, and 11 for device class V only.
- 4/ Offset is guaranteed adjustable to zero using a 10 k Ω potentiometer on both TRIM pins with the wiper connected to +V_S through a 250 k Ω resistor.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-93222
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 6

Device type	01
Case outline	Е
Terminal number	Terminal symbol
1	+V _S
2	TRIM
3	TRIM
4	OP AMP OUT
5	OP AMP -IN
6	OP AMP +IN
7	10 V IN
8	-V _S
9	Cos
10	CLOCK IN
11	FREQ OUT
12	DIGITAL GND
13	ANALOG GND
14	COMP -IN
15	COMP +IN
16	COMP REF

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		5962-93222
		REVISION LEVEL C	SHEET 7

4. VERIFICATION

- 4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.
 - 4.2.1 Additional criteria for device class M.
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.
- 4.3 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
- 4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
 - 4.4.1 Group A inspection.
 - a. Tests shall be as specified in table IIA herein.
 - b. Subgroups 7 and 8, in table I, method 5005 of MIL-STD-883 shall be omitted.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-93222
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 8

TABLE IIA. Electrical test requirements.

Test requirements	Subgroups	Subgr	roups
	(in accordance with	(in accord	ance with
	MIL-STD-883,	MIL-PRF-38	535, table III)
	method 5005, table I)		•
	Device	Device	Device
	class M	class Q	class V
Interim electrical	1	1	1
parameters (see 4.2)			
Final electrical	1,2,3,4,9 <u>1</u> /	1,2,3,4,9 <u>1</u> / <u>2</u> /	1,2,3, <u>1</u> / <u>2</u> / <u>3</u> /
parameters (see 4.2)			4,5,6,9,10,11
Group A test	1,2,3,4,9	1,2,3,4,9 <u>2</u> /	1,2,3, <u>2</u> /
requirements (see 4.4)			4,5,6,9,10,11
Group C end-point electrical	1	1	1,2,3, <u>3</u> /
parameters (see 4.4)			4,5,6,9,10,11
Group D end-point electrical	1	1	1,2,3,4,5,6,
parameters (see 4.4)			9,10,11
Group E end-point electrical			
parameters (see 4.4)			

^{1/} PDA applies to subgroup 1.

TABLE IIB. Burn-in and operating life test delta parameters. $T_A = +25$ °C. 1/2/

Parameters	Symbol	Condition	Delta limits
Quiescent current	±ISS	$V_S = \pm 15 \text{ V}, V_{IN} = 0.1 \text{ V}$	±1.7 mA
Op amp input offset voltage	Vos	V _{IN} = 0 V	±0.5 mV
Gain error	AE	f _{CLOCK} = 4 MHz, V _{IN} = 0.01 V, 9.4 V	±0.25% FSR
Clock input current	IC	CLOCK IN pin = 0 V	±2.5 μA
Leakage current	ΙL	V _{OUT} = 36 V	±1 μA

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-93222
DLA LAND AND MARITIME		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43218-3990		C	9

^{2/} See table I for specific subgroups 2, 3, 5, 6, 10, and 11 parameters applicable only to device class V.

 $[\]frac{3}{2}$ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be computed with reference to the zero hour electrical parameters (see table I).

 $[\]underline{1}'$ Deltas are performed at room temperature. $\underline{2}'$ 240 hour burn-in and 1,000 hour operating group C life test.

- 4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:
 - a. Test condition D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - b. $T_A = +125^{\circ}C$, minimum.
 - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - 4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).
 - a. End-point electrical parameters shall be as specified in table IIA herein.
 - b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at TA = +25°C, after exposure, to the subgroups specified in table IIA herein.
 - 5. PACKAGING
- 5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.
 - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.
 - 6.1.2 Substitutability. Device class Q devices will replace device class M devices.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.3 <u>Record of users</u>. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime -VA, telephone (614) 692-0547.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-93222
DLA LAND AND MARITIME		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43218-3990		C	10

- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DLA Land and Maritime -VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.
- 6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.
 - 6.6 Sources of supply.
- 6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime -VA and have agreed to this drawing.
- 6.6.2 <u>Approved sources of supply for device class M.</u> Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime -VA.

STANDARD	
MICROCIRCUIT DRAWIN	G

DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990

SIZE A		5962-93222
	REVISION LEVEL C	SHEET 11

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 11-02-28

Approved sources of supply for SMD 5962-93222 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime -VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at http://www.dscc.dla.mil/Programs/Smcr/.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-9322201MEA	24355 (2)	AD652SQ/883B
5962-9322201VEA	24355 (4)	AD652SQ/QMLV

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE <u>number</u>	Vendor name <u>and address</u>
24355 (2)	Analog Devices Route 1 Industrial Park P.O. Box 9106 Norwood, MA 02062 Point of contact: 804 Woburn Street Wilmington, MA 01887-3462
24355 (4)	Analog Devices Route 1 Industrial Park P.O. Box 9106 Norwood, MA 02062 Point of contact: 7910 Triad Center Drive Greensboro, NC 27409-9605

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.